World of PCB

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Engineering

Quickturn

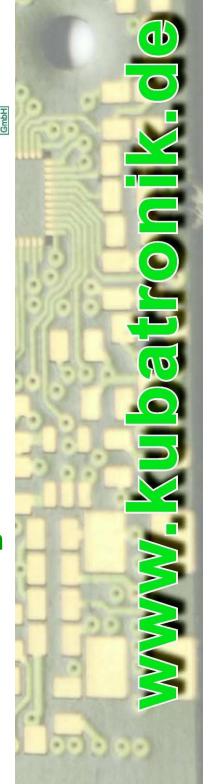
Components



Assembly (PCBA)

Prototyping

Mass-Production



Made in Germany





Established in 1980



Production in Geislingen / Steige (Germany)



55 Employees



Focus on High-Technology Rigidflex, Flex and HDI with High-Mix and Low-Volume



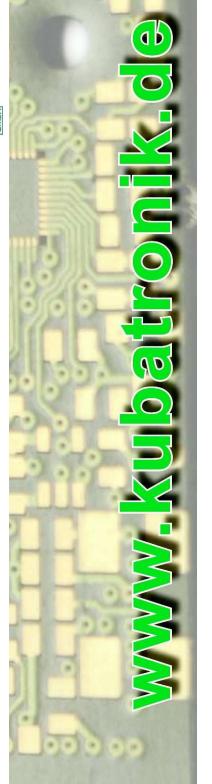
Quickturn and Express Production



Full Service and Complete Solutions (Components / PCBA)



Qualified and certified longtime Business-Partners for Mass Production and Assembly



News





Installation of completely new Direct Imaging System "Direct Imager 2050L Class MIVA 2050L DI" in May, 2019 for Inner- / Outerlayer and Soldermask.





Installation of completely new IT Infrastructure, Operating System (Hardware and Software) and Phone System (IP based) in May-June, 2019.



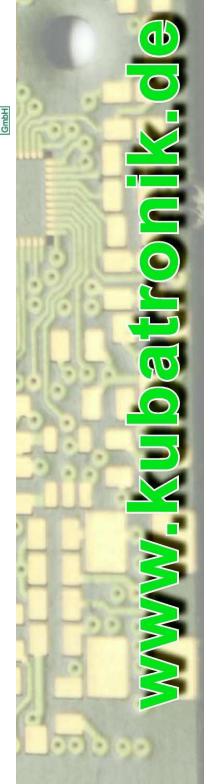




Installation of completely new Spray Coating System "Pluritec – Ecospray" and "Pluritec EcoDryer" in October, 2019.







News





Installation of a second Direct Imaging System "Direct Imager 2050L Class MIVA 2050L DI" with two heads in 2021 for Inner- / Outerlayer and Soldermask.



②

Installation of a "Free Form Scoring Machine - LENZ SLG" in 2021.





Installation of a X-RAY fluorescence XRF analysis system "Fischerscope XRAY XUL 220" in 2021.





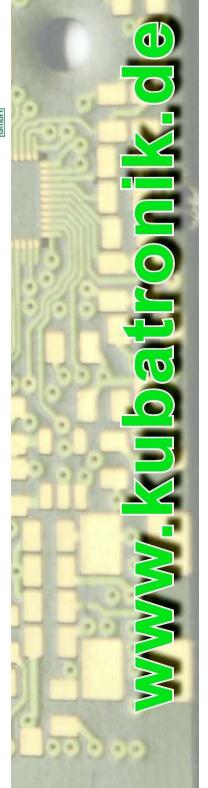
DIN EN ISO 9001:2015 (latest review)



DIN EN ISO 14001 (Environmental Management)



AS 9100 (Aerospace and Defence)



Investments – 2022 / 2023





Soda Developer for Soldermask



Additional Pressing System



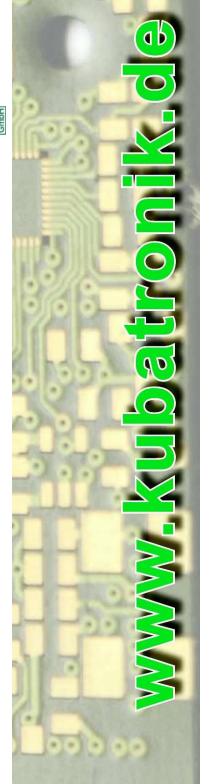
Cooling and climatization in the area of Pressing and Plasma



Additional ATG Electrical Test System (Flying-Probe)



Additional Laser Drilling / Cutting System



Provide Solutions





Engineering-Team with more than 50 years experience in PCB



650 new Layouts in 2022



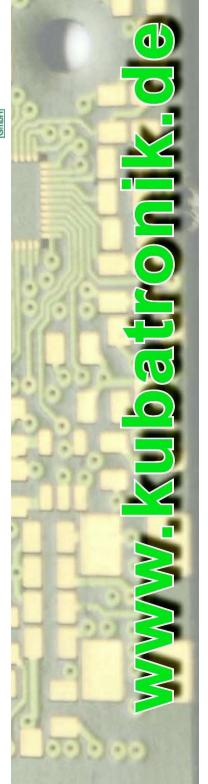
Test projects and test productions



Producing 75% from the production turnover in special and complex technologies (Flex, Rigidflex and HDI)

We enable your Vision





Capabilities





HDI - Blind / Buried / Stacked / Staggered Vias



Sequential BuildUp and Mixture BuildUp



Layer counts 30 plus



Max. thickness 4,8mm - special 5,6mm



Minimum line / space 75 μm (3 mil)



Via in Pad Plugging (Epoxy / Copper)



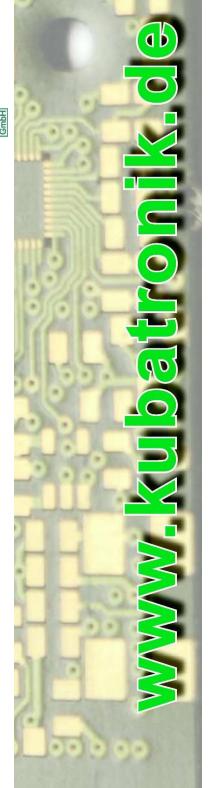
Micro Via Plugging (Epoxy / Copper)



Impedance controlled (including measuring protocol)



Laser cutting and drilling



Capabilities



Surface Finishes:

HASL (lead / leadfree)

Immersion Ni/Au

Immersion Silver

Immersion Tin

Soft Electrolytic Gold

Galvanic HardGold

ENTEK 106

OSP

ISIG

EPIG

ENEPIG



Materials:

FR4:

- -Isola
- -Ventec
- -lteq
- -Panasonic

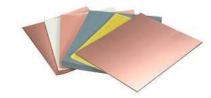
High Frequency / High Speed:

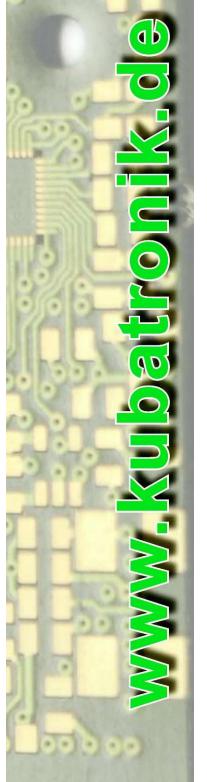
- -Rogers
- -Arlon
- -Nelco

Polyimid Glas

Polyimide

Other Special Materials on request





Backplane 26+ Layer



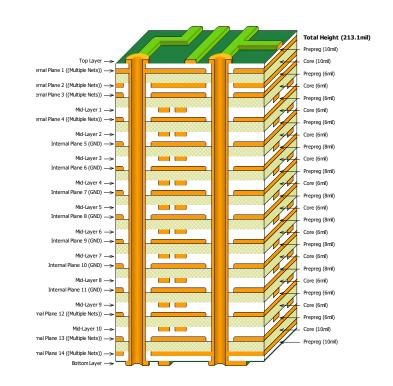
26-layer Backplane

Thickness 5,4mm

8 level backdrilling each site

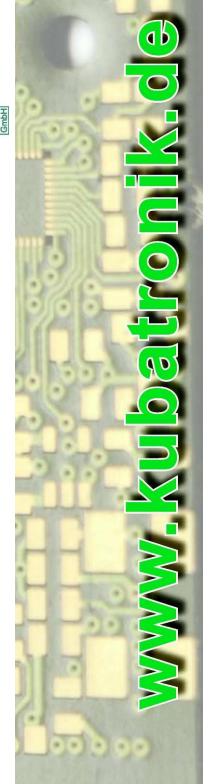
Impedance controlled

Board size 512 x 427mm





Also as RigidFlex Option with 6 flexible copper layer (3 x 125µm Polyimide Cores)!



HighSpeed + HighFrequency





20 layer Rogers / FR4 mix buildup

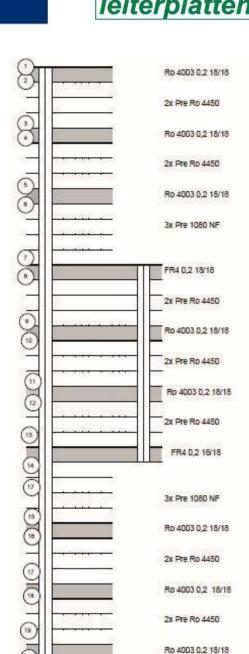
Thickness 4,5mm with aspect ratio 1:11

Edge Plating and plated slot holes

Line / Space 100µm

Impedance controlled

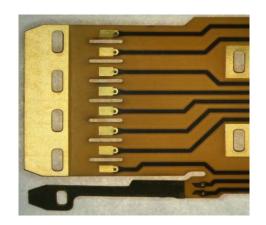
Sequential BuildUp (SBU) with buried vias and galvanic Ni/Au (hardgold) in innerlayer connector area



Exact + precise structures







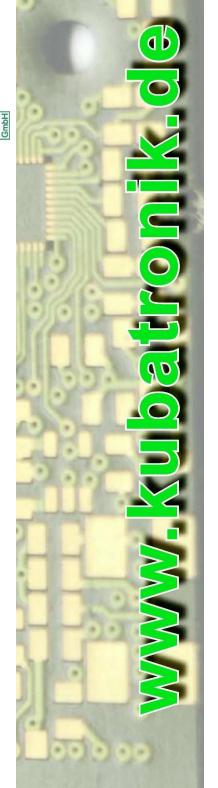
Lasered contour slot 0,25 mm

Lasered slot 0,1 mm

Base material AP8515 (25 µm polyimid)

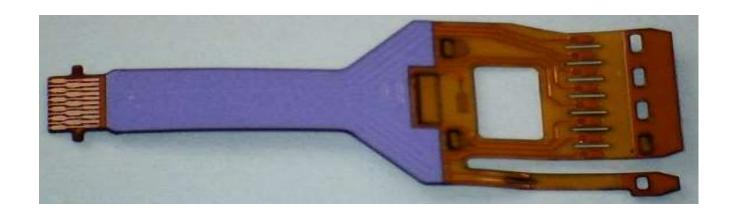
Over coverlayer rising contact pads with button technology

Connector area with stiffener and finishing galv. Ni/Au (hardgold)



Silver shielding



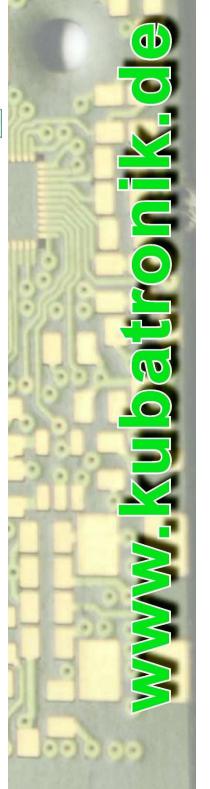


2-layer FPC with finishing ENEPIG

Silverfoil electrical connected as ground layer / shielding

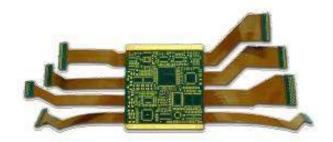
Base material AP8515 (25 µm polyimid)

Lasered contour

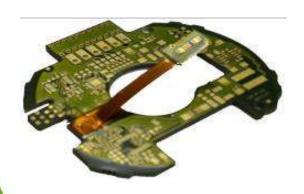


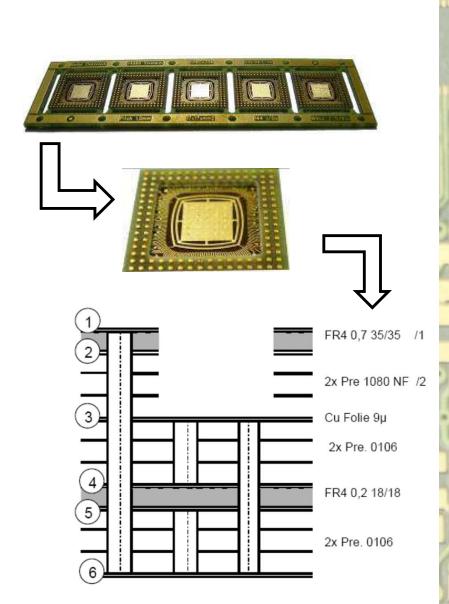
Technologies





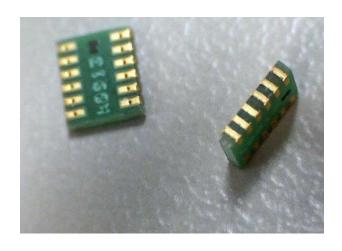


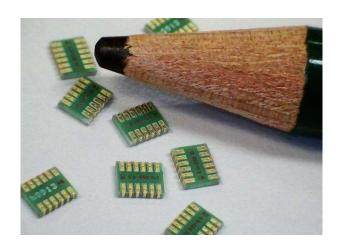




How small it may be?

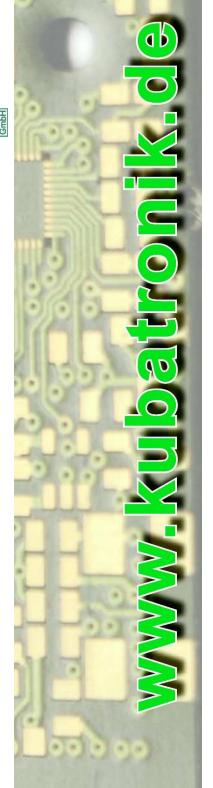






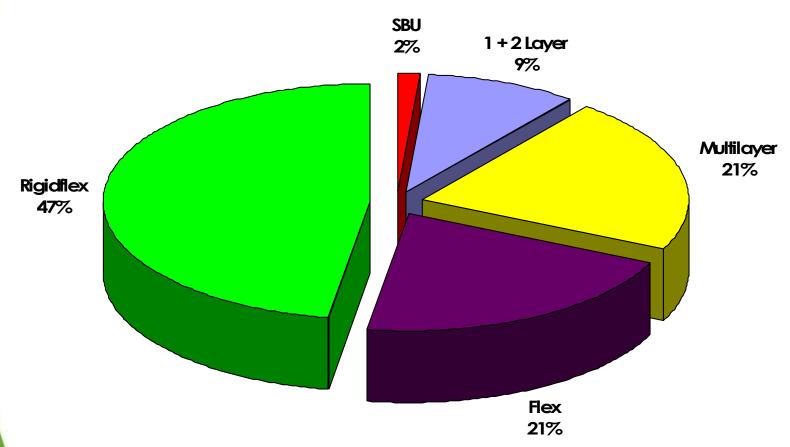
Whether rigid or flexible circuit boards, with or without edge metallization, we produce according to your requirements and laser the contour if necessary.

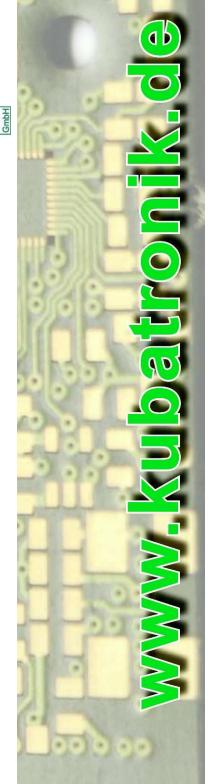




Product Mix

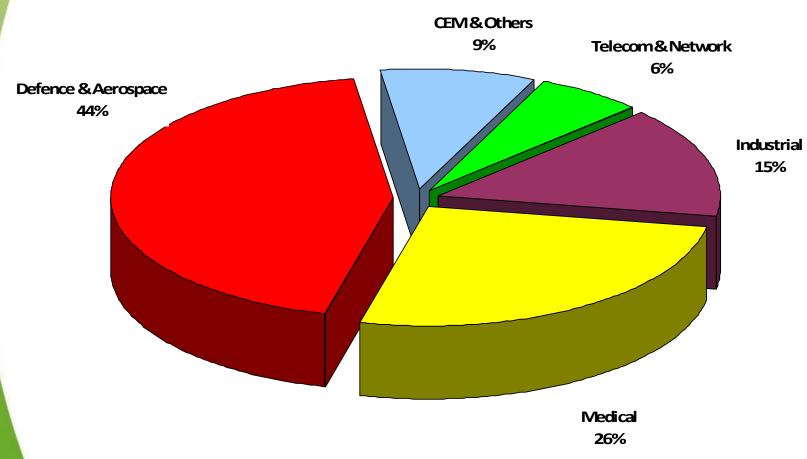
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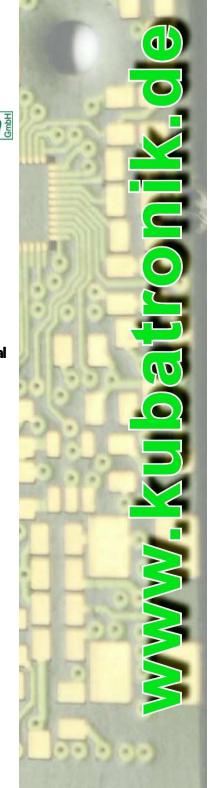




Markets

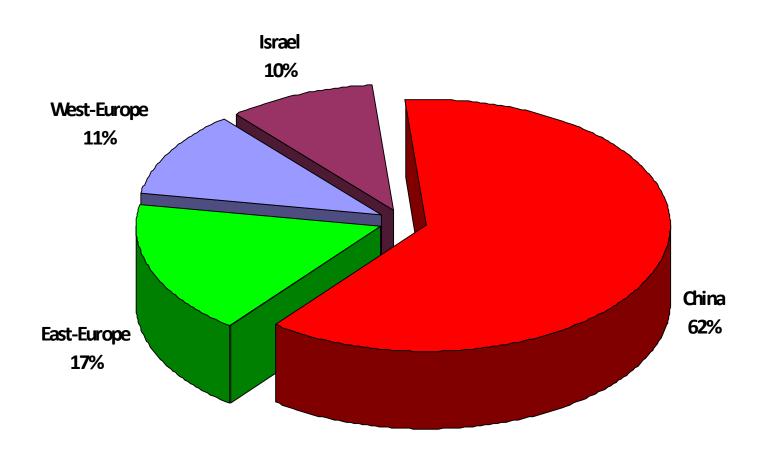
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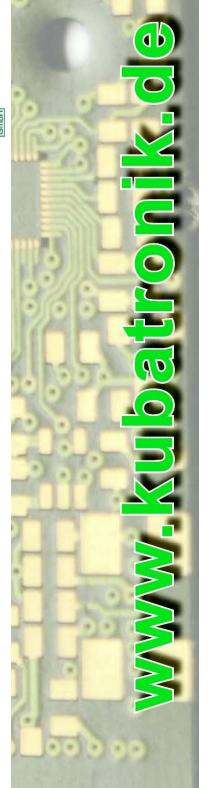




Origin of trading PCBs

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Qualifications / Certifications







UL-94V0 for Multilayer, Flex and RigidFlex







DIN EN ISO 9001:2015
DIN EN ISO 14001 (Environmental)
AS 9100 (Aerospace and Defence)



All relevant IPC Standards

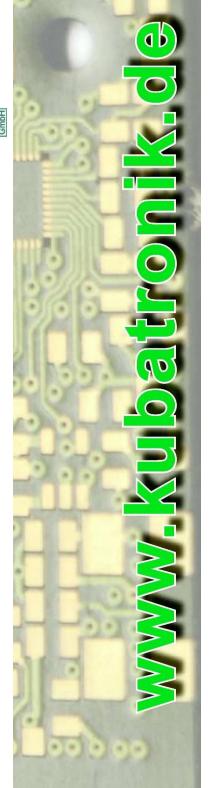


ROHS compliance





Member of EIPC and ZVEI



References





































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O ASTRIUM











the sensor people







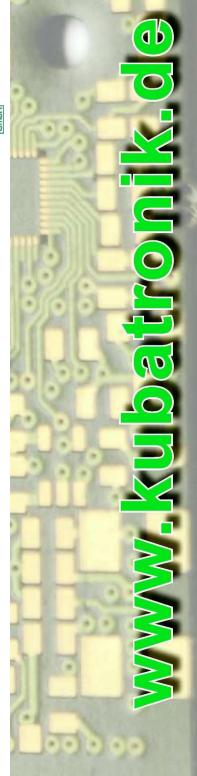












Together for your success



Thank You!



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